

General Description

The HSMA8076A is the high cell density SGT N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous rectification applications.

The HSMA8076A meet the RoHS and Halogen-Free compliant product requirement, 100% EAS guaranteed with full function reliability approved.

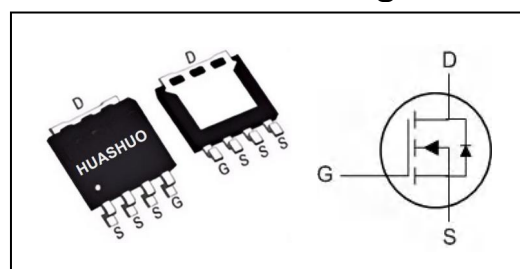
Features

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density SGT MOS Technology

Product Summary

V_{DS}	80	V
$R_{DS(ON),typ}$	1.75	m Ω
I_D	255	A

LFAK5X6 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	80	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	255	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	155	A
$I_D@T_A=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	35	A
$I_D@T_A=100^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	22	A
I_{DM}	Pulsed Drain Current ²	630	A
EAS	Single Pulse Avalanche Energy ³	180	mJ
I_{AS}	Avalanche Current	60	A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation ⁴	245	W
$P_D@T_A=25^{\circ}C$	Total Power Dissipation ⁴	5.2	W
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}C$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	24	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	0.51	$^{\circ}C/W$

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	80	---	---	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =30A	---	1.75	2.2	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	2	2.9	4	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =64V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =64V, V _{GS} =0V, T _J =55°C	---	---	5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	1.4	---	Ω
Q _g	Total Gate Charge (10V)	V _{DS} =40V, V _{GS} =10V, I _D =30A	---	101	---	nC
Q _{gs}	Gate-Source Charge		---	26	---	
Q _{gd}	Gate-Drain Charge		---	27	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =40V, V _{GS} =10V, R _G =3.3Ω, I _D =30A	---	22	---	ns
T _r	Rise Time		---	49	---	
T _{d(off)}	Turn-Off Delay Time		---	54	---	
T _f	Fall Time		---	41	---	
C _{iss}	Input Capacitance	V _{DS} =40V, V _{GS} =0V, f=1MHz	---	6560	---	pF
C _{oss}	Output Capacitance		---	1051	---	
C _{rss}	Reverse Transfer Capacitance		---	115	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,5}	V _G =V _D =0V, Force Current	---	---	100	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1.2	V
t _{rr}	Reverse Recovery Time	I _F =30A, dI/dt=100A/μs, T _J =25°C	---	76	---	nS
Q _{rr}	Reverse Recovery Charge		---	173	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=60A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.
- 6.The maximum current rating is package limited.

Typical Characteristics

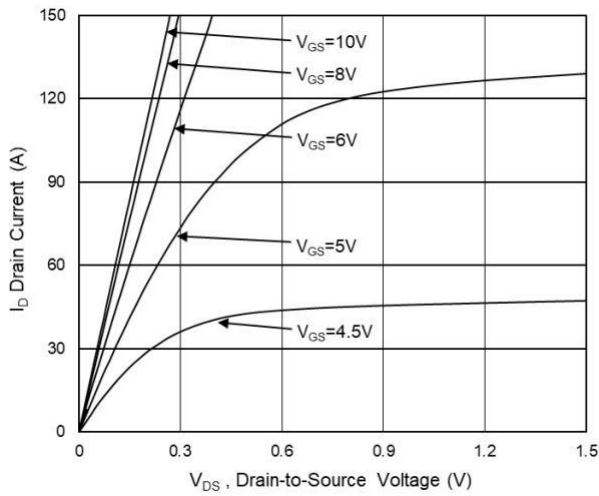


Fig.1 Typical Output Characteristics

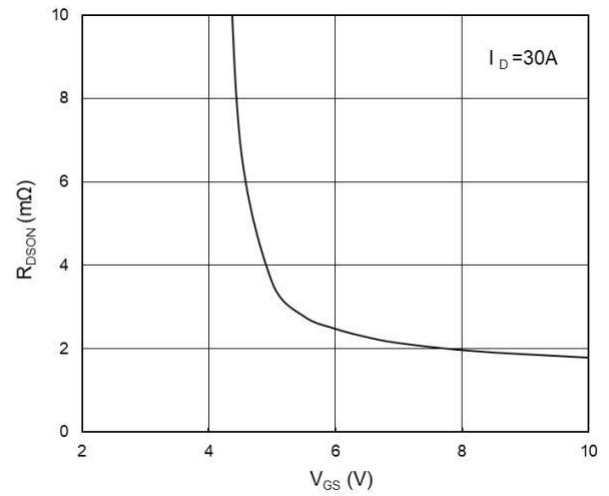


Fig.2 On-Resistance vs G-S Voltage

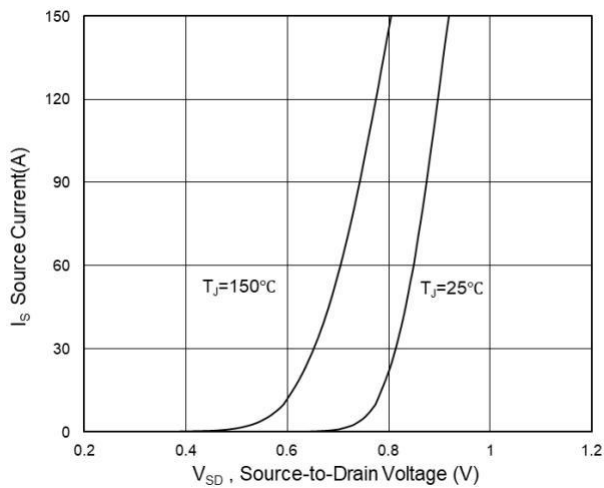


Fig.3 Source Drain Forward Characteristics

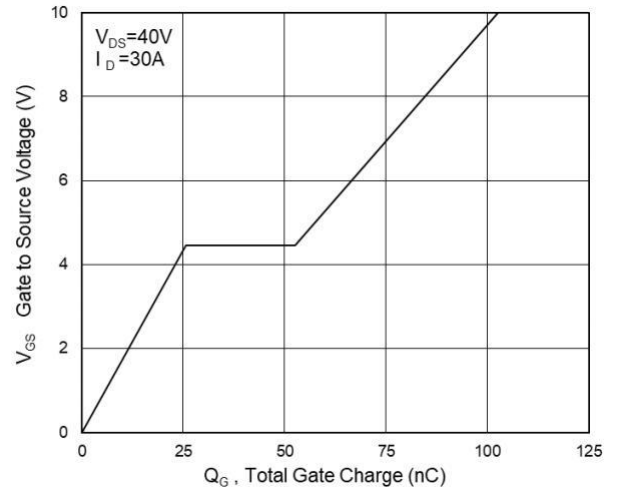


Fig.4 Gate-Charge Characteristics

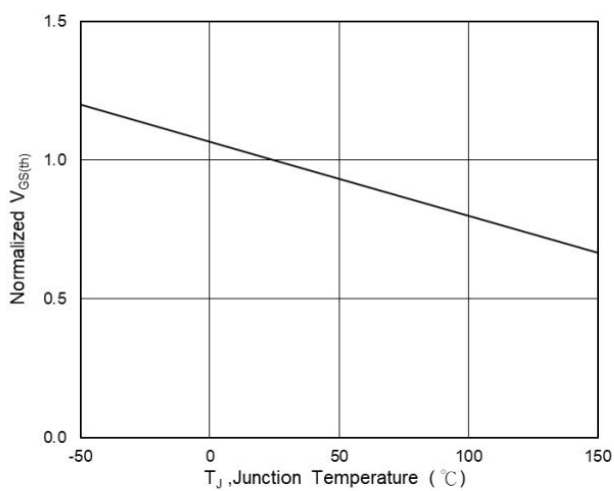


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

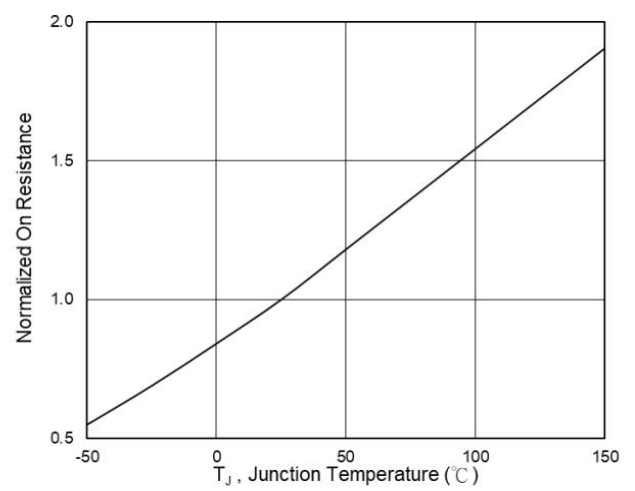


Fig.6 Normalized $R_{DS(on)}$ vs. T_J



N-Ch 80V Fast Switching MOSFETs

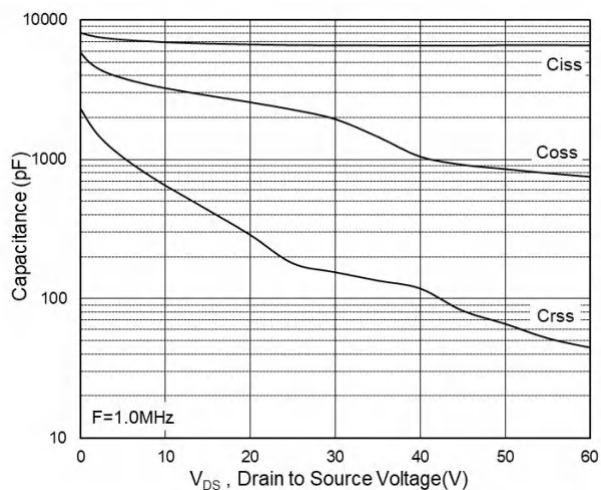


Fig.7 Capacitance

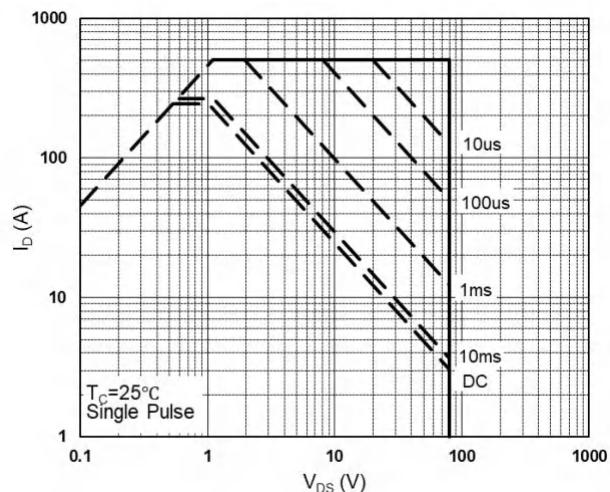


Fig.8 Safe Operating Area

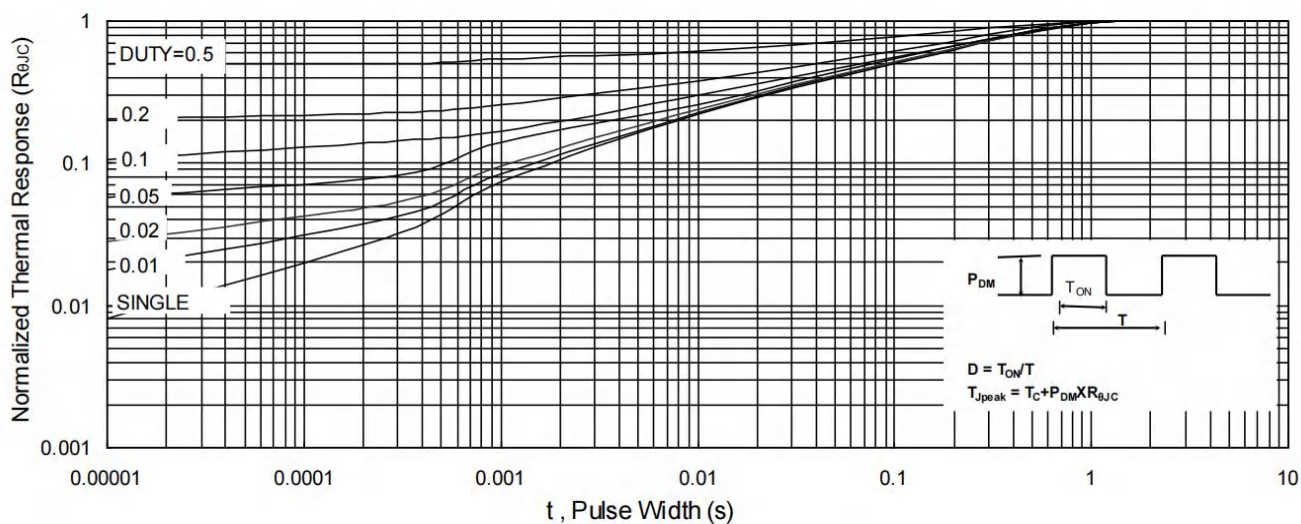


Fig.9 Normalized Maximum Transient Thermal Impedance

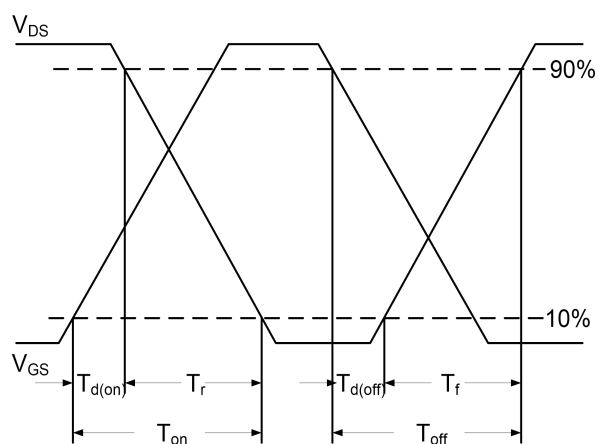


Fig.10 Switching Time Waveform

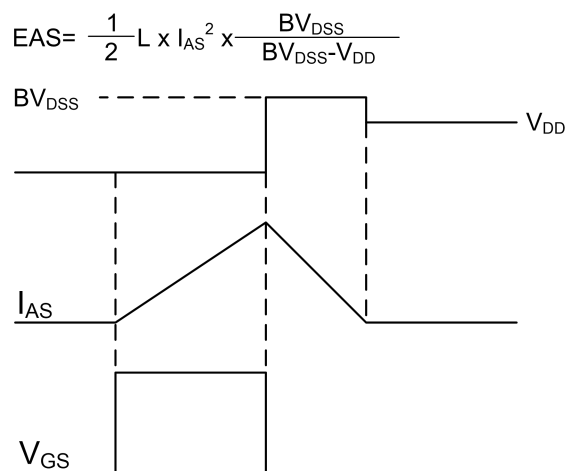
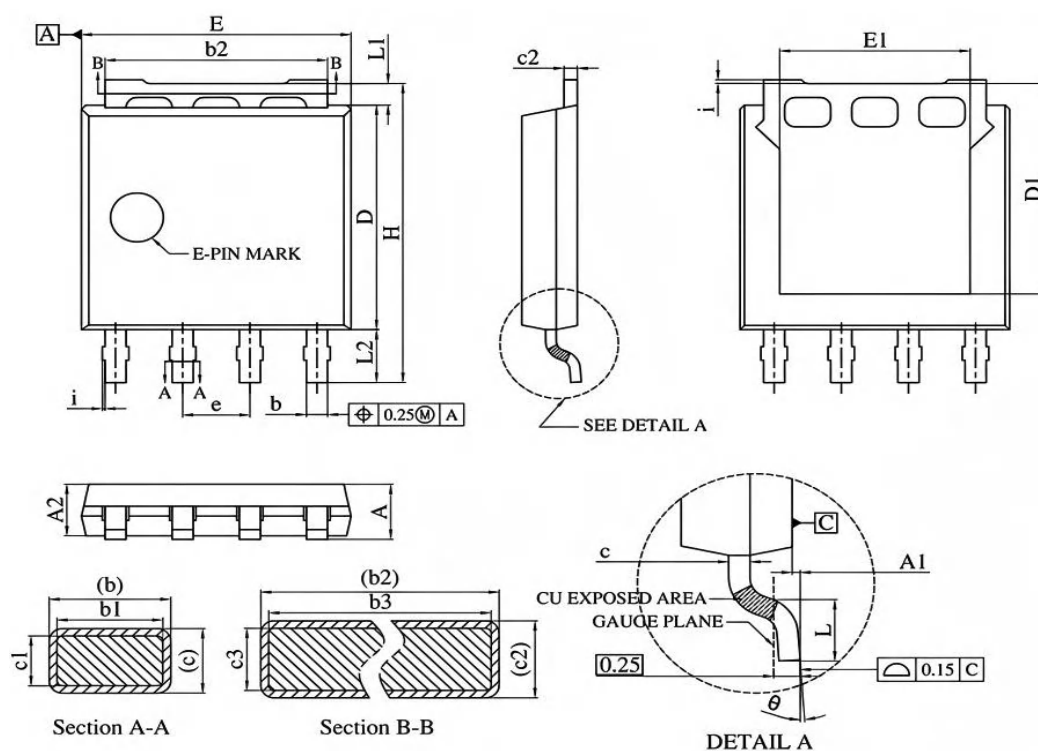


Fig.11 Unclamped Inductive Switching Waveform

Ordering Information

Part Number	Package code	Packaging
HSMA8076A	LFPAK5*6	2000/Tape&Reel

LFPAK5*6 Package Outline



COMMON DIMENSIONS(MM)			
SYMBOLS	MIN	NOM	MAX
A	1.00	-	1.20
A1	0	-	0.15
A2	0.98	1.05	1.12
b	0.35	0.40	0.50
b1	0.32	0.43	0.54
b2	4.02	4.21	4.40
b3	4.00	4.19	4.37
c	0.18	0.20	0.25
c1	0.17	0.20	0.23
c2	0.23	0.25	0.30
c3	0.22	0.25	0.28
D	4.45	-	4.70
D1	4.20	-	4.45
E	4.95	-	5.40
E1	3.50	-	3.70
e	1.27 BSC.		
H	5.95	-	6.25
i	-	-	0.25
L	0.40	-	0.85
L1	0.270	-	0.57
L2	0.80	-	1.30
θ	0°	-	8°

HSMA8076A Marking:

